Ref	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	4	("5880751" "6457794").pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/10 08:26
S2	1824	347/6,14,17,60.cds.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/20 13:14
S3	121099	((record\$3 print\$3) with head) same ((temperature heat\$3) control controlling)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/01 14:57
S4	1111	S2 and S3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/01 14:57
S5	4465	((record\$3 print\$3) with head) same ((temperature heat\$3) with pulse)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/01 15:27
S6	285	S2 and S5	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/01 14:58
S7	1433	((record\$3 print\$3) with nozzle) same ((temperature heat\$3) with pulse)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/01 14:58
S8	168	S2 and S7	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/01 14:58
59	83	("4791435").URPN.	USPAT	OR	ON	2005/07/01 15:15
S10	7	("4496824" "4544931" "4590488" "4664542" "4668965" "4692777" "4704620").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/07/01 15:16
S11	257	(((record\$3 print\$3) with head) same ((temperature heat\$3) with pulse)) same ((while during) with printing)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/05 07:15
S12	39	S2 and S11	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/01 15:28
513	9	("4313124" "4345262" "4459600" "4463359" "4558333" "4608577" "4723129" "4740796" "5581281").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/07/01 15:37

S14	86	(((record\$3 print\$3) with head) same ((temperature heat\$3) with pulse)) same (conduction)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/05 07:20
S15	1825	347/6,14,17,60.cds.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/05 07:16
S16	<u> </u>	S14 and S15	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/05 07:16
S17	421	(((record\$3 print\$3) with head) same ((temperature heat\$3) with (control pulse))) same ((on off) with head)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/05 07:22
S18	5	S14 and S17	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/05 07:21
S19	165	(((record\$3 print\$3) with head) same ((temperature heat\$3) with pulse)) same ((on off) same control)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/05 07:33
S20	62108	"347"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/05 07:23
S21	112	S19 and S20	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/05 07:23
522	15	S15 and S19	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM TDB	OR	ON	2005/07/05 07:23
S23	55	((print\$3) with head) same ((temperature heat\$3) with pulse) same (control with mode)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/05 07:44
S24	3	("4791435" "4970527" "5172134").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/07/05 07:41
S25	1	((print\$3) with head) same ((temperature heat\$3) with pulse) same (alternat\$3 with mode)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/05 08:22

S26		"20040090484"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/05 08:21
S27	1	2004-388868.NRAN.	DERWENT	OR	ON	2005/07/05 08:21
S28	403	((print\$3) with head) same ((temperature heat\$3) with pulse) same (speed)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/05 08:23
S29	44	((print\$3) with head) same ((temperature heat\$3) with optimum) same (speed)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/05 08:32
530	26	S20 and S29	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/05 08:23
S31	0	((print\$3) with head) same (temperature heat\$3) same (while with print\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/05 08:33
S32	3922	((print\$3) with head) same (temperature heat\$3) same ((while during) with print\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/05 08:33
533	174	S15 and S32	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/05 08:33
534	2730	((print\$3) with head) same (temperature heat\$3) with ((while during) with print\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/05 08:55
S35	146	S15 and S34	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/05 08:33
S36	580	(temperature with control) with (during with print\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/05 09:07
537	65	S15 and S36	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/05 08:55
S38	5	((temperature with control) with (during with print\$3)) same conduction	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/05 09:08

539	46	((temperature with control) with (during with print\$3)) and conduction	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/05 09:08
540	1825	347/6,14,17,60.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/05 09:39
S41	324	(heat\$3 with ((while during when) with (printing eject\$3))) same (temperature with control)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/05 09:41
S42	41	S40 and S41	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/05 09:52
543	19	((preheat\$ prepuls\$3) with (temperature with control)) same (during with printing)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/05 09:57
S44	16	((control with heat\$3) with (temperature with adjust\$4)) same (during with printing)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/05 10:12
S45	23	((control with heat\$3) same (temperature with adjust\$4)) same (during with printing)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/05 10:13
S46	47	((control same heat\$3) same (temperature with adjust\$4)) same (during with printing)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/05 10:13
S47	3	S40 and S46	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/05 10:13
S48	10	("4490728" "4712172" "4746937" "4791435" "4982199" "5036337" "5107276" "5109234" "5168284" "5381164").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/01/10 08:38
549	16	("5736995").URPN.	USPAT	OR	ON	2006/01/10 08:39
S50	6	("4490728" "5036337" "5107276" "5736995" "6390585" "6422677").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/01/10 08:40
S51	0	("6808243").URPN.	USPAT	OR	ON	2006/01/10 08:56
S52	0	347/6,14,17,60	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/10 08:57

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S53	1904	347/6,14,17,60.cds.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/10 08:57
S54	143	(((heat\$3 pre) near4 pulse) same ((print\$3 fir\$3 record\$3 near4 pulse))) same ((print\$3 record) with mode)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/10 08:59
S55	38	S53 and S54	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/10 08:59
S56	2	"5168284".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/19 10:48
S57	17	(US-20040090484-\$).did. or (US-5880751-\$ or US-5736995-\$ or US-4704620-\$ or US-5581281-\$ or US-5861895-\$ or US-5255011-\$ or US-4539571-\$ or US-5339098-\$ or US-5072237-\$ or US-5337093-\$ or US-4791435-\$ or US-5107276-\$ or US-6474764-\$ or US-5559535-\$ or US-4668965-\$ or US-5168284-\$).did.	US-PGPUB; USPAT	OR	ON	2006/06/19 10:49
S58	4	(printhead near4 chip with heater) same (conductive near5 substrate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/19 14:19
S59	66667	"347"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/19 14:18
S60	13	(thermal\$3 with conductive with substrate) same (silicon with resis\$4 with heater)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/19 14:20
S61	7	S59 and S60	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/19 14:21
S62	3357	ceramic with substrate same heater	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/19 14:24
S63	175	S59 and S62	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/19 14:21
S64	138	S63 not canon.as.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/19 14:22

S65	0	S64 and bubblejet	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/19 14:23
566	1	S64 and bubble\$3jet	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/19 14:23
S67	540	(thermal\$3 with ceramic with substrate) same heater	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/19 14:25
S68	61	S59 and S67	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/19 14:24
S69	1890	(thermal\$3 with conduct\$4) same (heater and substrate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/19 14:26
S70	285	S59 and S69	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/19 14:32
S71	40	bohorquez.in. and hewlett.as.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON .	2006/06/19 14:32
S72	15	S59 and S71	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/19 14:35
S73	2	(printhead with (chip die)) same (conductive adj substrate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/19 14:35
S74	2	(printhead near5 (chip die)) same (conductive adj substrate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/19 14:36
S75	103	(printhead near5 (chip die)) same (conductive with substrate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/19 14:47
576	74	S59 and S75	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/19 14:36

S77	30	(printhead near5 (chip die)) same (heatsink (heat with sink))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/19 14:38
578	73	(printhead near5 (chip die)) same ((alumin\$5 ceramic) with substrate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/19 14:55
579	68	S59 and S78	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/19 14:48
580	68	S79 and thermal\$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/19 14:50
581	8	S79 and (thermal\$4 with conduct\$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/19 14:50
582	31	("4496793" "4680859" "4711804" "4763188" "4896168" "4942408" "5292688" "5369056" "5473513" "5510273" "5528457" "5538586" "5545473" "5581121" "5614763" "5627407" "5672545" "5751552" "5778523" "5834848" "5894173" "5895971" "5900675" "5936304" "5952719" "5960260" "6014317" "6046496" "6049124" "6071427" "6186622").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/06/19 14:52
S83	10	(printhead near5 (chip die)) same ((alumin\$5 ceramic) with substrate) and cte .	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/19 14:56
584	19	(US-20040090484-\$).did. or (US-6474764-\$ or US-5736995-\$ or US-5559535-\$ or US-5880751-\$ or US-5861895-\$ or US-4791435-\$ or US-5307093-\$ or US-5168284-\$ or US-5107276-\$ or US-4704620-\$ or US-5072237-\$ or US-4539571-\$ or US-5339098-\$ or US-4668965-\$ or US-5255011-\$ or US-581281-\$ or US-6250738-\$ or US-6502926-\$).did.	US-PGPUB; USPAT	OR	ON	2006/06/19 14:57
S85	1	S84 and (conduct\$4 with substrate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/19 14:57
S86	110	(printhead with (chip die)) with (cool\$3 "heat transfer" (conductive with substrate))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/19 15:07
S87	621	(printhead with temperature with control\$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/19 16:41
S88	66667	"347"/\$.ccis.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/19 15:14

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S89	100	(conductive with (substrate layer)) and S87	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/19 15:15
S90	94	S88 and S89	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/19 15:15
S91	67	S90 and (operat\$3 with temperature)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/19 15:37
S92	2	S90 and (desir\$3 with temperature)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/19 15:36
S93	13	("4908638" "4950365" "4960050" "4977410" "5036337" "5053792" "5343231" "5367325" "5426458" "5519429" "5538758" "5784666" "5894314").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/06/19 16:39
S94	1009	(printhead with temperature with (control\$4 method))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/19 16:45
S95	715	(printhead with temperature with (control\$4 pre\$3heat\$3))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/19 16:41
S96	530	S88 and S95	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/19 16:42
S97	48	(printhead with (die chip)) same (temperature with control)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/19 16:46
598	39	((coefficient with thermal with expansion) with (substrate)) same (printhead with (chip die))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/19 16:48
599	5	((coefficient with thermal with expansion) with (conduct\$4)) same (printhead with (chip die))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/19 16:48
S10 0	1	((heat with transfer) with (substrate)) same (printhead with (chip die))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/19 16:49

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S10 1	3	(conductive with filled with polymer) and (printhead with (chip die))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/19 16:50
S10 2	2	(filled with ceramic) and (printhead with (chip die))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/19 16:50
S10 3	22	(US-20040090484-\$).did. or (US-4704620-\$ or US-6109719-\$ or US-5736995-\$ or US-5107276-\$ or US-4980702-\$ or US-5255011-\$ or US-4539571-\$ or US-5339098-\$ or US-5072237-\$ or US-5330993-\$ or US-5194877-\$ or US-6502926-\$ or US-5581281-\$ or US-4791435-\$ or US-4668965-\$ or US-5168284-\$ or US-6250738-\$ or US-5880751-\$ or US-6474764-\$ or US-5861895-\$ or US-5559535-\$).did.	US-PGPUB; USPAT	OR	ON	2006/06/20 07:48
S10 4	2	S103 and (heat near5 conduction)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/20 07:50
S10 5	0	S103 and (substrate near5 conduction)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/20 07:50
S10 6	4	S103 and (substrate near5 conduct\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/20 08:03
S10 7	2	(pre\$3heat\$3 near4 pulse) same (print\$2head with temperature with adjust\$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/20 08:05
S10 8	0	(pre\$3heat\$3) with (print\$2head with temperature with adjust\$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/20 08:05
S10 9	4	(pre\$3heat\$3) same (print\$2head with temperature with adjust\$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/20 08:08
S11 0	220	(pre\$3heat\$3 (warm near3 up)) same (printhead with temperature)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/20 08:09
S11 1	17994	347/20-67.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/20 08:09
S11 2	114	S110 and S111	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/20 08:09

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S11 3	1154	347/14.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/20 08:09
S11 4	18	S110 and S113	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/20 08:14
S11 5	470	(heat\$3 near6 printing) same (conduct\$3 near6 substrate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/20 08:15
S11 6	177	(heating near6 printing) same (conduct\$3 near6 substrate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/20 08:15
S11 7	66697	"347"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/20 08:15
S11 8	38	S116 and S117	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/20 08:19
S11 9	194	((warm with up) (pre\$2heat)) same (inkjet (bubble near3 jet))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR .	ON	2006/06/20 08:31
S12 0	166	((warm with up) (pre\$2heat)) same (inkjet (bubble near3 jet)) and (conduct\$3 substrate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/20 08:33
S12 1	68	S117 and S120	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/20 08:32
S12 2	4	S113 and S120	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/20 08:32
S12 3	48	((warm with up) (pre\$2heat)) same (Inkjet (bubble near3 jet)) and (conduct\$3 with substrate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON .	2006/06/20 08:35
S12 4	10	(((warm with up) (pre\$2heat)) same printhead) and ((heat with conduct\$3) same (substrate layer))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/20 08:37

[613]	22	(heat with send with 2) some (substants lave) and Cdd2	LIC DCDUD.	00	100	1 2006/06/20 20 27
512 5	23	(heat with conduct\$3) same (substrate layer) and S113	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/20 08:37
S12 6	7	("4791435" "4910528" "5107276" "5175565" "5760797" "6139125" "6234599").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/06/20 08:42
S12 7	4850	(temperature with (control\$4 adjust\$4)) same ((heater resistor) with (pre\$2pulse warm\$3))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/20 08:49
S12 8	100	S117 and S127	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/20 08:49
S12 9	8	("4490728" "4982199" "5109234" "5122812" "5414245" "5428376" "5475405" "5815180").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/06/20 09:18
S13 0	0	(transducer with (die chip)) same (temperature with (control adjust\$4)) and (switch\$3 with (heat\$3 and eject\$3))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/20 09:33
S13 1	85	(transducer with (die chip)) same (temperature with (control adjust\$4))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/20 09:36
S13 2	66697	"347"/\$.ccis.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/20 09:39
S13 3	4	S131 and S132	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TD8	OR	ON	2006/06/20 09:37
S13 4	5	("4380771" "4463359" "4565859" "5172139" "5412410").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/06/20 09:39
S13 5	0	(heater with (pre\$2pulse and main\$2pulse)) same (heat with conduct\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/20 09:41
S13 6	0	(heater with (pre\$2pulse and main\$2pulse)) and (heat with conduct\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/20 09:41
513 7		(pre\$2pulse and main\$2pulse) same (heat with conduct\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/20 09:41

S13 8		(pre\$2pulse and main\$2pulse) and (heat with conduct\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT;	OR	ON	2006/06/20 09:41
S13 9	64	(pre\$2pulse main\$2pulse) and (heat with conduct\$3)	IBM_TDB US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT;	OR	ON	2006/06/20 09:41
S14 0	23	S132 and S139	IBM_TDB US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/20 09:55
S14 1	302	(temperature near4 control) and (utiliz\$3 with heat with conduction)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/20 09:56
S14 2	11	S132 and S141	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/20 09:56
S14 3	8	("5751302" "5774137" "5880751" "5943069" "5943070" "6024439" "6302507" "6439696").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/06/20 10:03
S14 4	582	347/17.cds.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/20 10:36
S14 5	376	(temperature with control) and S144	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/20 10:26
S14 6	8	((adjacent with (die chip)) same heat\$3) and \$144	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/20 10:30
S14 7	0	((adjacent with (die chip)) and pre\$2pulse) and S144	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/20 10:31
S14 8	8	((adjacent with (die chip)) and pre\$2heat\$3) and S144	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/20 10:31
S14 9	7	("4403229" "4791435" "5175565" "5629578" "6059394" "6135656" "6219153").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/06/20 10:32
S15 0	49565	((print\$3head eject\$4) with (die chip element))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/20 10:37

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S15 1	176	((print\$3head eject\$4) with (die chip element)) and S144	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/20 10:51
S15 2	4	"5880751".pn. "6457794".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/20 10:52
S15 3	17	("4791435" "4899180" "4910528" "5075690" "5107276" "5132709" "5220345" "5265315" "5422662" "5428376" "5477245" "5760797" "5815180" "5838341" "5851075" "5966149" "6068363").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/06/20 11:09
S15 4	10	("4313124" "4345262" "4459600" "4463359" "4558333" "4704618" "4723129" "4740796" "5175565" "5760797").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/06/20 13:04
S15 5	5	("6068363").URPN.	USPAT	OR	ON	2006/06/20 13:09
S15 6	49	((heat with conduct\$3) with (base)) same ((dle chip) with array)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/20 13:16
S15 7	66697	"347"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/20 13:15
S15 8	3	S156 and S157	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/20 13:16
S15 9	17452	((heat with conduct\$3) with (base))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/20 13:17
S16 0	1061	((heat with conduct\$3) with (base)) same (temperature with (control\$4 adjust\$3))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/20 13:19
S16 1	6	S157 and S160	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/20 13:18
S16 2	374	((thermal with conduct\$3) with (base)) same (temperature with (control\$4 adjust\$3))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/20 13:45
S16 3	9	S157 and S162	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/20 13:19

S16 4	65	((die chip) near6 array) and 347/40.cds.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/20 13:51
S16 5	38	S164 and conduct\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/20 13:46
S16 6	. 47	S164 and temperature	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/20 13:49
S16 7	48	S164 and (temperature conduction)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/20 13:49
S16 8	21	S164 and (temperature and conduction)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/20 13:50
516 9	6	S164 and (temperature same conduction)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/20 13:49
517 0	841	((die chip) with (position placement)) and (thermal near6 conduction)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/20 13:57
.S17 1	40	S157 and S170	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/20 13:52
S17 2	0	((die chip) with (cool43)) and (thermal near6 conduction)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/20 13:57
S17 3	3014	((die chip) with (heat\$3)) and (thermal near6 conduction)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/20 13:58
S17 4	83	S157 and S173	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON .	2006/06/20 13:58
S17 5	2429	((die chip) near5 (heat\$3)) and (thermal near6 conduction)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/20 14:01

S17 6	68	S157 and S175	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/20 13:58
S17 7	85	((warm\$3 pre\$2heat\$3) near5 (die chip transducer)) and (thermal near6 conduction)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/20 14:02
S17 8	7	S157 and S177	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/20 14:02

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